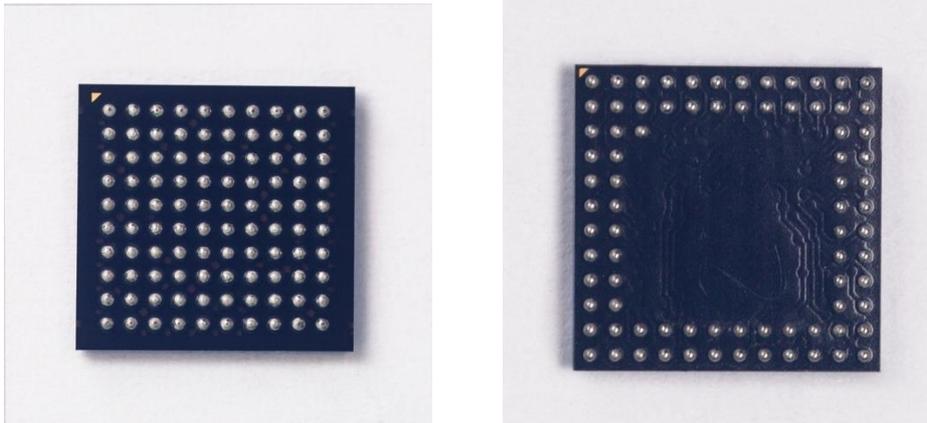




## Media Release

### **UTAC announces license for iBGA packaging technology**



**Singapore, 04 April 2019** – UTAC Holdings Ltd. (“UTAC”), a global semiconductor test and assembly services provider is pleased to announce that it has, via its subsidiary UTAC Headquarters Pte. Ltd. secured a license for relevant patents relating to imaging ball grid array (iBGA) packaging technology from a patent licensing company. Under the patent license, UTAC and its affiliates have full rights to manufacture, use and sell products utilising iBGA packaging technology that is claimed in the licensed patents.

The licensed technology will be primarily used for the assembly of image sensor packages for automotive and industrial camera applications, as well as other sectors such as security, computing and consumer. Both primary market sectors are growing rapidly, particularly as more automakers include multiple imaging cameras in their vehicles to support advanced driver assistance systems (ADAS). The use of these cameras is expected to grow rapidly and significantly as vehicles ultimately become fully autonomous. The industrial market sector is also showing strong growth as a result of rapidly growing applications such as machine vision.

UTAC is already experienced in high volume image sensor assembly and test, especially for Tier One customers in the industrial, consumer and automotive marketplaces. These customers demand very high quality, something that UTAC ensures through their Class 10 cleanroom environment that is dedicated to the assembly of front-end wafers into packages (including the new iBGA) and subsequent testing.

As image sensing technology advances, UTAC provides designers with the ability to migrate to smaller formfactors with an optimized substrate design.

The new iBGA packaging technology is ready for manufacturing and is qualified to relevant automotive standards. Several Tier One automotive device suppliers have already expressed an interest in utilizing this technology.

-End-

#### **About UTAC Holdings Ltd**

UTAC Holdings Ltd is a leading independent provider of assembly and test services for a broad range of semiconductor chips. We offer a full range of semiconductor assembly and test services in these key product categories: analog, mixed-signal and logic, and memory. Our customers are primarily fabless companies, integrated device manufacturers and wafer foundries. We are headquartered in Singapore, with production facilities located in Singapore, Thailand, Taiwan, China, Indonesia, and Malaysia. We have a global sales network across United States, Japan, China and Taiwan, rest of Asia and Europe, with sales offices in each of these regions.

#### **For media enquiries, please contact:**

UTAC  
Carol Chiang Sian Meng  
E: [carol\\_chiangsm@utacgroup.com](mailto:carol_chiangsm@utacgroup.com)  
Tel: +65 67142220

Publitek Limited  
Birgit Schöniger / Helen Chung  
E: [birgit.schoeniger@publitek.com](mailto:birgit.schoeniger@publitek.com)/ [helen.chung@publitek.com](mailto:helen.chung@publitek.com)  
Tel: +44 (0) 208 429 6554 / +44 (0) 203 475 1858

**Ref. UTACP001\_A\_EN**